



# Material Composition Declaration

## EPC21603

Company Name	Efficient Power Conversion (EPC)	Issue Date:	1/11/2024
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	2.0 mg	Type of Product:	eGaN IC

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	1.5982	79.3071	81.8329	793071
	Silicon oxide	7631-86-9	0.0070	0.3477		3477
	Silicon nitride	12033-89-5	0.0026	0.1270		1270
	Gallium nitride	25617-97-4	0.0079	0.3937		3937
	Aluminum	7429-90-5	0.0114	0.5666		5666
	Aluminum nitride	24304-00-5	0.0017	0.0831		831
	Titanium	7440-32-6	0.0004	0.0202		202
	Titanium nitride	25583-20-4	0.0016	0.0787		787
	Copper	7440-50-8	0.0002	0.0095		95
	Tungsten	7440-33-7	0.0022	0.1109		1109
	Polyimide		0.0159	0.7885	7885	
Under Bump Metal	Titanium	7440-32-6	0.0002	0.0107	0.0531	107
	Copper	7440-50-8	0.0009	0.0424		424
Solder Bump	Tin	7440-31-5	0.3486	17.2989	18.1140	172989
	Silver	7440-22-4	0.0146	0.7246		7246
	Copper	7440-50-8	0.0018	0.0906		906
Sum in total:			2.0151	100.0000	100.0000	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.